

Global 3D IC Packaging Market Size study & Forecast, by Packaging Technology (3D wafer-level chip-scale packaging (WLCSP), 3D TSV), by End-User (Consumer Electronics, Aerospace and Defense, Medical Devices, Communications and Telecom, Automotive), and Regional Analysis, 2022-2029

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Abstracts

The global 3D IC Packaging Market is valued at approximately USD XX billion in 2021 and is anticipated to grow with a healthy growth rate of more than XX % over the forecast period 2022-2029. 3D IC Packaging is a packaging technology. It has major application across various end-user industries including Consumer Electronics, Aerospace and Defense, Medical Devices, Communications and Telecom, Automotive. In this methodology, active chips are integrated by die stacking for the shortest interconnect and smallest package footprint. Also, for numerous IC inside the same package. The 3D IC Packaging market is expanding because of factors such as the rising demand for electronic products and miniaturization of electronic devices.

According to Indian Brand Equity Foundation in 2022, the domestic electronic production in India has grown during 2014-2015 to 2020-2021 from USD 29 billion to USD 67 billion. The IT sector in India is one of the largest contributors with a 9% contribution to GDP. Also, according to the Statista in 2022, revenue in the global consumer electronics market accounts USD 1,062 billion. Whereas rising adoption of high-end computing servers and data centers and strategic initiatives by key-players create lucrative opportunities for the market. However, higher initial investment cost hampers the market growth throughout the forecast period of 2022-2029.

The key regions considered for the Global 3D IC Packaging Market study include Asia

Pacific, North America, Europe, Latin America, and the Rest of the World. Asia Pacific is deemed as the dominated and fastest growing region in terms of revenue, owing to the increasing demand from end-use industries, growing penetration of market players and rising adoption of electronic and smart technologies. It includes presence of major companies across the region such as TSMC, SMIC, UMC, and South Korea's Samsung. Taiwan's leading chip foundry which boosts the market growth on the forecast period

Major market players included in this report are:

Taiwan Semiconductor Manufacturing Company Limited

Samsung Electronics Co., Ltd.

ASE Group

Amkor Technology

Intel Corporation

Siliconware Precision Industries Co. Ltd (SPIL)

GlobalFoundries

Invensas

Powertech Technology Inc.

Micron technology, Inc

Recent Developments in the Market:

In May 2021: Intel intends to invest USD 3.5 billion in upgrading its Rio Rancho plant and increasing its workforce by more than 35% at the sprawling complex, one of the company's three largest US manufacturing hubs. It is expanding its New Mexico operations to produce new generations of chips based on its Foveros 3D packaging technology, which could help the company reclaim its semiconductor industry leadership.

In October 2021: Cadence Design Systems, Inc. has released the Integrity 3D-IC platform. It is the industry's first high-capacity, all-in-one 3D-IC platform, combining 3D implementation, system analysis, and design planning into a single, unified cockpit.

Global 3D IC Packaging Market Report Scope:

Historical Data 2019-2020-2021

Base Year for Estimation 2021

Forecast period 2022-2029

Report Coverage Revenue forecast, Company Ranking, Competitive Landscape, Growth factors, and Trends

Segments Covered Packaging Technology, End-user, Region

Regional Scope North America; Europe; Asia Pacific; Latin America; Rest of the World

Customization Scope Free report customization (equivalent up to 8 analyst's working

hours) with purchase. Addition or alteration to country, regional & segment scope*

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within countries involved in the study.

The report also caters detailed information about the crucial aspects such as driving factors & challenges which will define the future growth of the market. Additionally, it also incorporates potential opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:

By Packaging Technology:

3D wafer-level chip-scale packaging (WLCSP),
3D TSV

By End-user:

Consumer Electronics,
Aerospace and Defense,
Medical Devices,
Communications and Telecom,
Automotive

By Region:

North America
U.S.
Canada
Europe
UK
Germany
France
Spain
Italy
ROE
Asia Pacific
China
India
Japan

Australia
South Korea
RoAPAC
Latin America
Brazil
Mexico
Rest of the World

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